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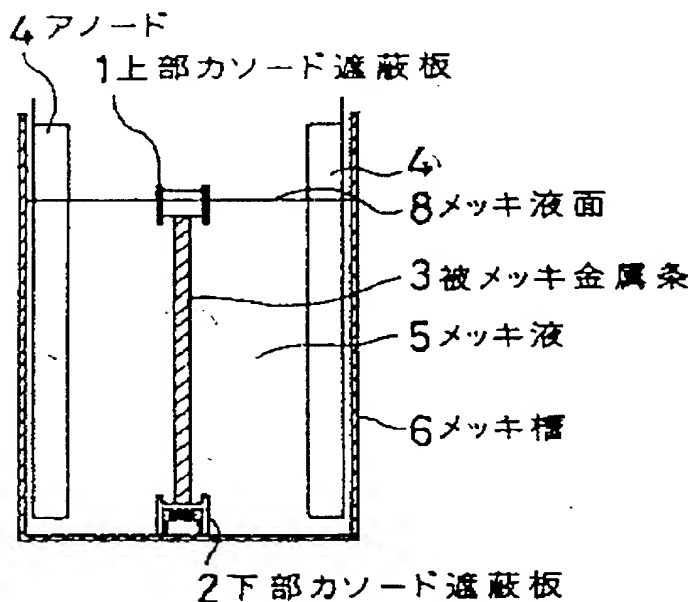
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**(54) METHOD AND
DEVICE FOR
DIFFERENTIAL
THICKNESS PLATING**

(57) Abstract:

PURPOSE: To uniformize the plating thickness in a transverse direction by completely breaking the current on a thick plating side and thin plating side and passing a high density current to the former and a low-density current to the latter in a stage for executing differential thickness plating.

CONSTITUTION: Anodes 4 are disposed on both sides in a plating cell 6 and a metallic strip 3 to be plated is placed at the center thereof. Cathode shielding plates 1 and 2 which come into contact at all times with both transverse ends of the strip are provided to break the current on the thick plating side and the thin plating side. The flow of the current on the thick plating side to the thin plating side is prohibited in this way and the



promoted in this way and the plating can be executed by maintaining the high-density current on the thick plating side and the low- current density on the thin plating side at all times. The differential thickness plated product having the uniform plating thickness in the transverse direction is obtd. in the plating cell of the same liquid compsn.

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